

ML22Q374/ML22Q394 SSOP16 Reference Board User's Manual



Notes

- 1) The information contained herein is subject to change without notice.
- 2) When using LAPIS Technology Products, refer to the latest product information (data sheets, user's manuals, application notes, etc.), and ensure that usage conditions (absolute maximum ratings, recommended operating conditions, etc.) are within the ranges specified. LAPIS Technology disclaims any and all liability for any malfunctions, failure or accident arising out of or in connection with the use of LAPIS Technology Products outside of such usage conditions specified ranges, or without observing precautions. Even if it is used within such usage conditions specified ranges, semiconductors can break down and malfunction due to various factors. Therefore, in order to prevent personal injury, fire or the other damage from break down or malfunction of LAPIS Technology Products, please take safety at your own risk measures such as complying with the derating characteristics, implementing redundant and fire prevention designs, and utilizing backups and fail-safe procedures. You are responsible for evaluating the safety of the final products or systems manufactured by you.
- 3) Descriptions of circuits, software and other related information in this document are provided only to illustrate the standard operation of semiconductor products and application examples. You are fully responsible for the incorporation or any other use of the circuits, software, and information in the design of your product or system. And the peripheral conditions must be taken into account when designing circuits for mass production. LAPIS Technology disclaims any and all liability for any losses and damages incurred by you or third parties arising from the use of these circuits, software, and other related information.
- 4) No license, expressly or implied, is granted hereby under any intellectual property rights or other rights of LAPIS Technology or any third party with respect to LAPIS Technology Products or the information contained in this document (including but not limited to, the Product data, drawings, charts, programs, algorithms, and application examples, etc.). Therefore LAPIS Technology shall have no responsibility whatsoever for any dispute, concerning such rights owned by third parties, arising out of the use of such technical information.
- 5) The Products are intended for use in general electronic equipment (AV/OA devices, communication, consumer systems, gaming/entertainment sets, etc.) as well as the applications indicated in this document. For use of our Products in applications requiring a high degree of reliability (as exemplified below), please be sure to contact a LAPIS Technology representative and must obtain written agreement: transportation equipment (cars, ships, trains, etc.), primary communication equipment, traffic lights, fire/crime prevention, safety equipment, medical systems, servers, solar cells, and power transmission systems, etc. LAPIS Technology disclaims any and all liability for any losses and damages incurred by you or third parties arising by using the Product for purposes not intended by us. Do not use our Products in applications requiring extremely high reliability, such as aerospace equipment, nuclear power control systems, and submarine repeaters, etc.
- 6) The Products specified in this document are not designed to be radiation tolerant.
- 7) LAPIS Technology has used reasonable care to ensure the accuracy of the information contained in this document. However, LAPIS Technology does not warrant that such information is error-free and LAPIS Technology shall have no responsibility for any damages arising from any inaccuracy or misprint of such information.
- 8) Please use the Products in accordance with any applicable environmental laws and regulations, such as the RoHS Directive. LAPIS Technology shall have no responsibility for any damages or losses resulting non-compliance with any applicable laws or regulations.
- 9) When providing our Products and technologies contained in this document to other countries, you must abide by the procedures and provisions stipulated in all applicable export laws and regulations, including without limitation the US Export Administration Regulations and the Foreign Exchange and Foreign Trade Act..
- 10) Please contact a ROHM sales office if you have any questions regarding the information contained in this document or LAPIS Technology's Products.
- 11) This document, in part or in whole, may not be reprinted or reproduced without prior consent of LAPIS Technology.

(Note) "LAPIS Technology" as used in this document means LAPIS Technology Co., Ltd.

Copyright 2013 – 2020 LAPIS Technology Co., Ltd.

LAPIS Technology Co., Ltd.

2-4-8 Shinyokohama, Kouhoku-ku, Yokohama 222-8575, Japan https://www.lapis-tech.com/en/

1. Overview

This is the instruction manual for ML22Q374/ML22Q394 SSOP16 Reference Board.

ML22Q374/ML22Q394 SSOP16 Reference Board supports following functions in combination with Sound Device Control Board.

- 1. Voice Playback by ML22Q374/ML22Q394.
- 2. Writing voice data into ML22Q374/ML22Q394.

Please notice that the LSI written by this reference board can be used only as a prototype.

It is not guaranteed as a mass-produced quality.

2. Operating Suggestions

It is the operating suggestions for ML22Q374/ML22Q394 SSOP16 Reference Board.

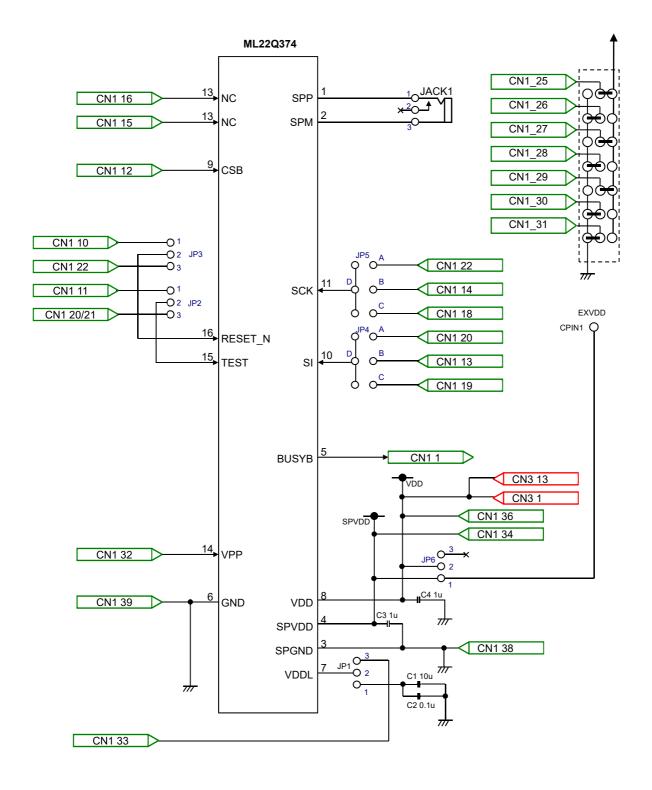
- 1. Please do not supply a power to sound device control board, when the reference board is being mounted on it.
- 2. Please do not supply a power to sound device control board, when the LSIs are being mounted in the socket on the reference board. Then please confirm the aspect of the LSIs. The pin no.1 of LSIs must be placed at left near side of the socket.
- 3. LAPIS Technology will not provide any support for this board, but the board can be exchanged with a new product only when it has an initial failure.



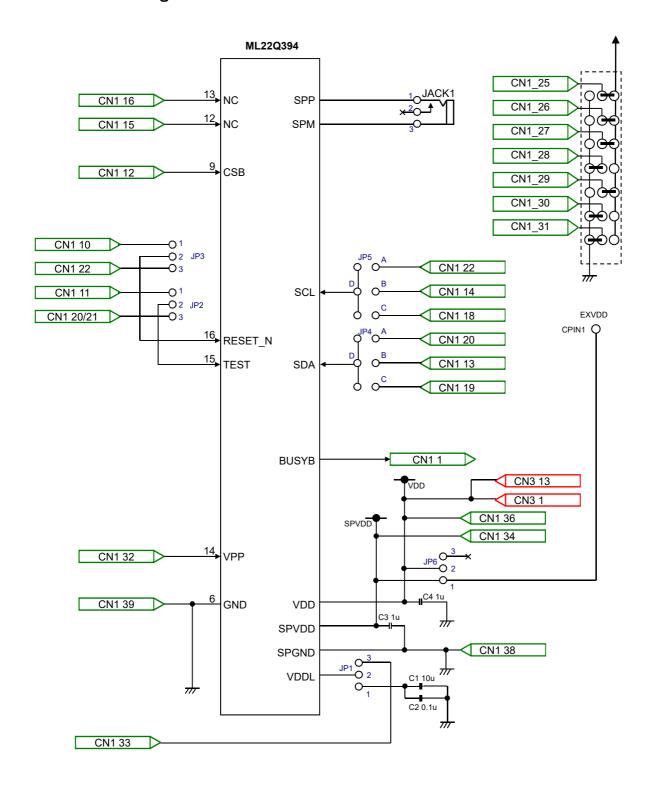
3. Reference Board

3.1 Circuit Diagram

3.1.1 Circuit Diagram for ML22Q374

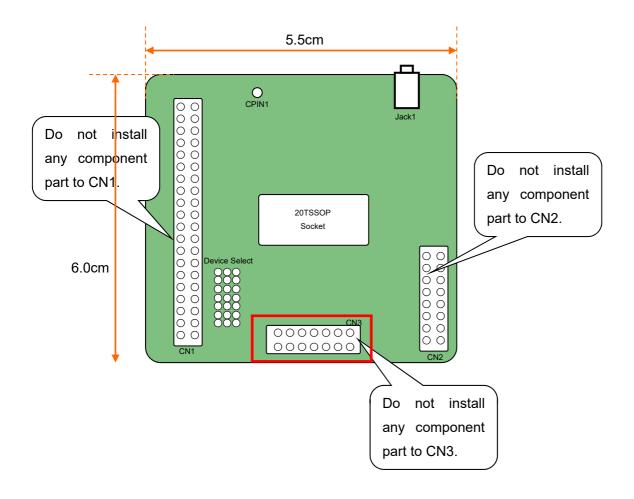


3.1.2 Circuit Diagram for ML22Q394



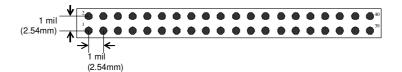
3.2 Rough PCB layout

ML22Q374/ML22Q394 SSOP16 Reference Board rough layout is described.



3.3 CN1 connector specification

This is connector for connecting to ML22Q374/ML22Q394 control signal lines. It has two rows 40 pins.



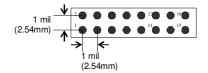
3.4 CN1 connector pin connections

CN1 Pin No			ML22Q374		ML22Q394		
		Connect LSI	LSI Pin No	LSI Pin Name	Connect LSI	LSI Pin No	LSI Pin Name
1	I/O	ML22Q374	5	BUSYB	ML22Q394	5	BUSYB
2	I/O	_	_	NC	_	_	NC
3	I/O	_	_	NC	_	_	NC
4	I/O	_	1	NC	_	1	NC
5	I/O	_	l	NC	_	1	NC
6	I/O	_	1	NC	_	1	NC
7	I/O	_		NC	_		NC
8	I/O	_	l	NC	_	1	NC
9	I/O	_		NC	_		NC
10	I/O	JP3-1	20	RESET_N	JP3-1	20	RESET_N
11	I/O	JP2-1	19	TEST	JP2-1	19	TEST
12	I/O	ML22Q374	13	CSB	ML22Q394	13	CSB
13	I/O	JP4-B	14	SI	JP4-B	14	SDA
14	I/O	JP5-B	15	SCK	JP5-B	15	SCL
15	I/O	ML22Q374	16	NC	ML22Q394	16	NC
16	I/O	ML22Q374	17	NC	ML22Q394	17	NC
17	I/O	_	1	NC	_	1	NC
18	I/O	JP5-C	15	SCK	JP5-C	15	SCL
19	I/O	JP4-C	14	SI	JP4-C	14	SDA
20	I/O	JP4-A	14	SI	JP4-A	14	SDA
		JP2-3	19	TEST	JP2-3	19	TEST

		ML22Q374			ML22Q394		
CN1 Pin No		Connect LSI	LSI Pin No	LSI Pin Name	Connect LSI	LSI Pin No	LSI Pin Name
21	I/O	JP4-A	14	JP4-A	JP4-A	14	SDA
		JP2-3	19	JP2-3	JP2-3	19	TEST
22	I/O	JP5-A	15	JP5-A	JP5-A	15	SCL
		JP3-3	20	JP3-3	JP3-3	20	RESET_N
23	I/O		1		_	_	NC
24	I/O				_	_	NC
25	Board Select	VDD	1	VDD	VDD	_	_
26	Board Select	GND		GND	VDD	_	_
27	Board Select	VDD		VDD	VDD	_	_
28	Board Select	GND	1	GND	GND	_	_
29	Board Select	VDD	_	VDD	VDD	_	_
30	Board Select	GND	-	GND	GND	_	_
31	Board Select	GND	1	GND	GND	_	_
32	VPP	ML22Q374	18	ML22Q374	ML22Q394	18	VPP
33	VDD	JP1-3	7	JP1-3	JP1-3	7	VDDL
34	VDD	ML22Q374	4	ML22Q374	ML22Q394	4	SPVDD
35	VDD	ML22Q374	8	ML22Q374	ML22Q394	8	VDD
36	VDD	ML22Q374	8	ML22Q374	ML22Q394	8	VDD
37	VDD()		1		_	_	NC
38	GND	ML22Q374	3	ML22Q374	ML22Q394	3	SPGND
39	GND	ML22Q374	6	ML22Q374	ML22Q394	6	GND
40	GND	ML22Q374	6	ML22Q374	ML22Q394	6	GND

3.5 CN2 connector specification

CN2 is connecting to all ML22Q374/ML22Q394 terminals. It has two rows 16 pins.

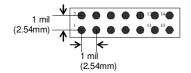


3.6 CN2 connector pin connections

CN2 Pin No	LSI Pin No	LSI Pin Name (ML22Q374)	LSI Pin Name (ML22Q394)
1	1	SPP	SPP
2	2	SPM	SPM
3	3	SPGND	SPGND
4	4	SPVDD	SPVDD
5	5	BUSYB	BUSYB
6	6	GND	GND
7	7	VDDL	VDDL
8	8	VDD	VDD
9	13	CSB	CSB
10	14	SI	SDA
11	15	SCK	SCL
12	16	NC	NC
13	17	NC	NC
14	18	VPP	VPP
15	19	TEST	TEST
16	20	RESET_N	RESET_N

3.7 CN3 connector specification

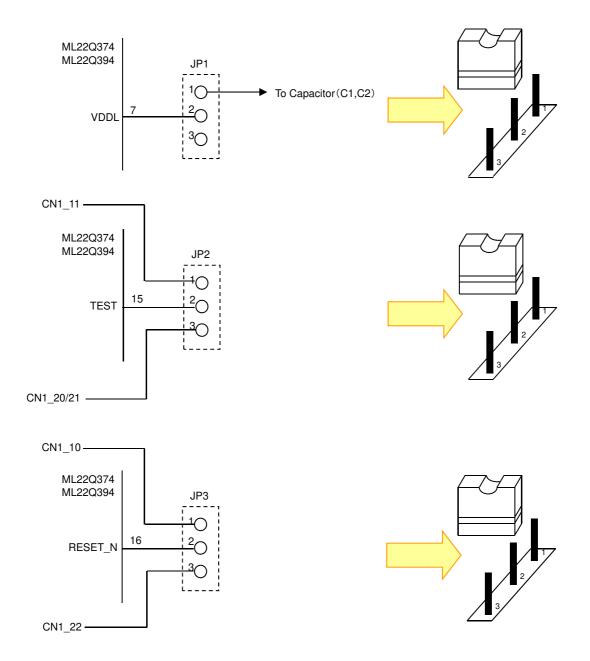
CN3 is connecting to all ML22Q374/ML22Q394 terminals. It has two rows 14 pins.

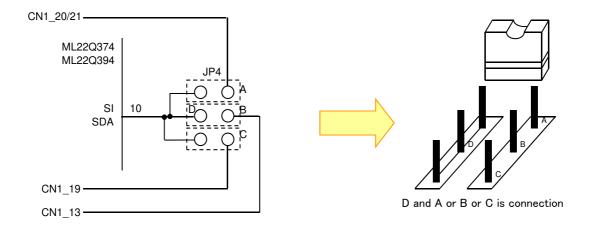


3.8 CN3 connector pin connections

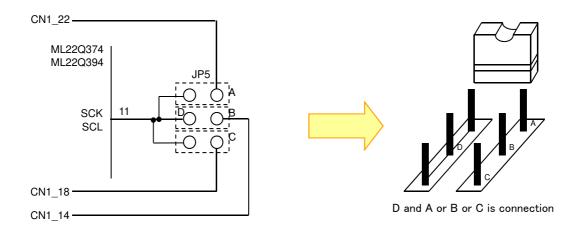
CN3 Pin No	LSI Pin No	LSI Pin Name (ML22Q374)	LSI Pin Name (ML22Q394)
1	8 JP6-2	VDD	VDD
2	6	GND	GND
4	3	SPGND	SPGND
6			
8			
10			
12			
3	18	VPP	VPP
5	20	RESET_N	RESET_N
7	19	TEST	TEST
9	7	VDDL	VDDL
11	NC	-	-
13	8	VDD	VDD
	JP6-2		
14	NC	-	-

3.9 Jumper specifications

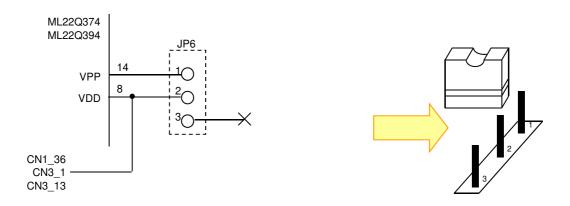




JP4 settings depend on the connected board. For jumper setting, refer to ②Device Select in 3.10. Jumper Pin Setting.



JP5 settings depend on the connected board. For jumper setting, refer to ②Device Select in 3.10. Jumper Pin Setting.



3.10 Jumper Pin Setting

①Playback/Write

Jumper Pin No.	Playback	Write / Verify	
JP1	Fixed on the left side	Fixed on the right side	
JP2	Fixed on the left side	Fixed on the right side	
JP3	Fixed on the left side	Fixed on the right side	
JP6	Fixed on the left side	Fixed on the left side	

2 Device Select

This is the jumper setting when connecting to SDCB2.

Jumper Pin No.	ML22Q374	ML22Q394	
JP4	Fixed on the Apin and Dpin	Fixed on the Bpin and Dpin	
JP5	Fixed on the Apin and Dpin	Fixed on the Bpin and Dpin	

This is the jumper setting when connecting to SDCB3.

Jumper Pin No.	ML22Q374	ML22Q394	
JP4	Fixed on the Apin and Dpin	Fixed on the Cpin and Dpin	
JP5	Fixed on the Apin and Dpin	Fixed on the Cpin and Dpin	

※Fixed on the left side :Jumper 1pin = 2pin
※Fixed on the right side :Jumper 2pin = 3pin

Revision History

		Page		
Revision NO.	Date	Previous Edition	Current Edition	Description
1	2013/01/08	-	-	First edition
2	2020/11/04	-	1	Removed the description of ML22374, ML22Q384, ML22384, ML22394.
		1	1	Change the description of the Notes.
				Company name changed to Lapis Technology Co., Ltd.
		6	6	3.1.2 Circuit Diagram for ML22Q384/ML22384 Removed term.
		13	13	Added explanation that JP4 has different settings depending on the board to be connected.
				Added explanation that JP5 has different settings depending on the board to be connected.
		14	14	Added jumper settings when connecting SDCB3.

ML22Q374/ML22Q394

SSOP16

Reference Board User's Manual

Issue Date: November 4, 2020

Revision: 2

@2013-2020 LAPIS Technology Co., Ltd.